

Abstract

Invention Title: METHOD, SYSTEM, AND APPARATUS FOR PROCESSING
WAFER

An embodiment of the present disclosure provides a wafer processing method including preparing a wafer having a notch portion at one side thereof, aligning the wafer by analyzing image information of the notch portion captured by a vision camera, and processing the notch portion using a notch wheel so that a certain region of the notch portion has a preset thickness.

[Figure 3]